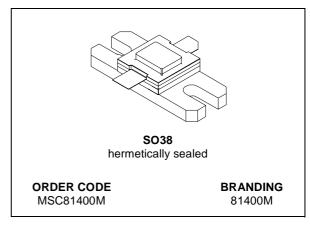


# MSC81400M

# RF & MICROWAVE TRANSISTORS AVIONICS APPLICATIONS

- REFRACTORY/GOLD METALLIZATION
- RUGGEDIZED VSWR 25:1
- INTERNAL INPUT/OUTPUT MATCHING
- LOW THERMAL RESISTANCE
- METAL/CERAMIC HERMETIC PACKAGE
- P<sub>OUT</sub> = 400 W MIN. WITH 6.4 dB GAIN

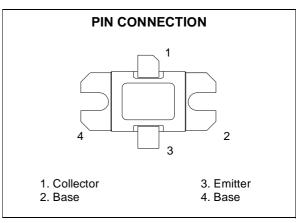


#### **DESCRIPTION**

The MSC81400M "Super Power" transistor is a high peak pulse power device specifically designed for DME/TACAN avionics applications.

This device is capable of withstanding a minimum 25:1 load mismatch condition at any phase angle under full rated conditions.

The MSC81400M is housed in the unique BIG-PAC™ hermetic metal/ceramic package with internal input/output matching structures.



## **ABSOLUTE MAXIMUM RATINGS** $(T_{CASE} = 25 \degree C)$

	,	_	_
Symbol	Parameter	Value	Unit
P <sub>DISS</sub>	Power Dissipation* $(T_C \le 80  ^{\circ}C)$	1000	W
Ic	Device Current*	28	Α
V <sub>cc</sub>	Collector-Supply Voltage*	55	V
Tj	Junction Temperature (Pulsed RF Operation)	250	°C
T <sub>STG</sub>	Storage Temperature	- 65 to +200	°C

#### THERMAL DATA

R <sub>th(j-c)</sub>	Junction -Case Thermal Resistance*	0.12	°C/W
----------------------	------------------------------------	------	------

<sup>\*</sup> Applies only to rated RF amplifier operation

October, 5 2001 1/4

## **ELECTRICAL SPECIFICATION** (T<sub>CASE</sub> = 25 °C)

## **STATIC**

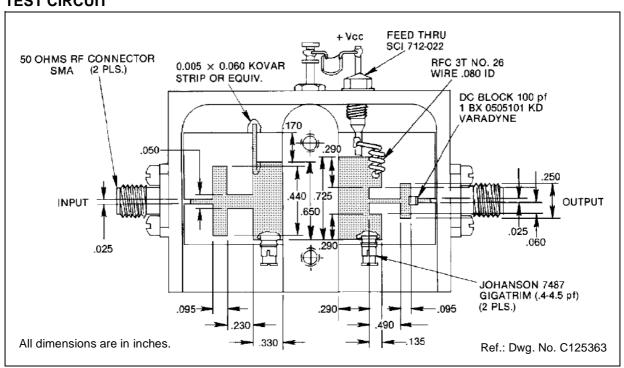
Symbol	Test Conditions	Min.	Тур.	Max.	Unit
BV <sub>CBO</sub>	Ic = 15mA I <sub>E</sub> = 0mA	65			V
BV <sub>EBO</sub>	I <sub>C</sub> = 0mA I <sub>E</sub> = 1mA	3.5			V
BV <sub>CER</sub>	$I_C = 50$ mA $R_{BE} = 10\Omega$	65			V
ICES	V <sub>CE</sub> = 50V			35	mA
h <sub>FE</sub>	V <sub>CE</sub> = 5V I <sub>C</sub> = 1A	15		120	

### **DYNAMIC**

Symbol		Min.	Тур.	Max.	Unit	
Pout	f = 1025 - 1150MHz	V <sub>CC</sub> = 50V	400	450		W
G <sub>P</sub>	f = 1025 - 1150MHz	P <sub>OUT</sub> = 400 W V <sub>CC</sub> = 50V	6.4			dB
η <sub>C</sub>	f = 1025 - 1150MHz	P <sub>OUT</sub> = 400 W V <sub>CC</sub> = 50V	35	40		%

Note: Pulse Width = 10  $\mu$ Sec Duty Cycle = 1%

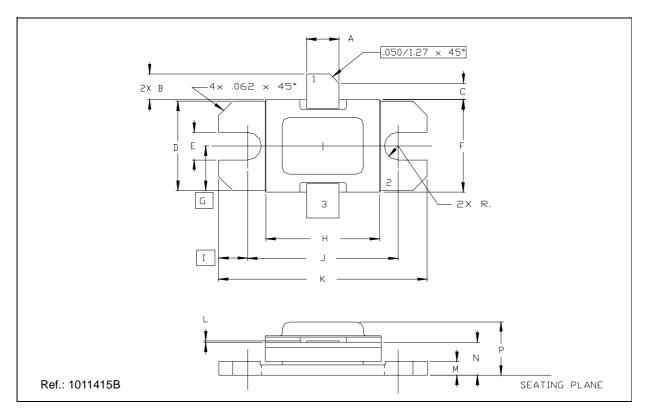
## **TEST CIRCUIT**



2/4

# SO38 (.400 X .500 2/L HERM. W/FLG.) MECHANICAL DATA

DIM.	mm			Inch			
	MIN.	TYP.	MAX	MIN.	TYP.	MAX	
А	3.43		3.68	0.135		0.145	
В	2.54		3.05	0.100		0.120	
С	1.27			0.050			
D	9.55		10.06	0.376		0.396	
Е	2.79		3.30	0.110		0.130	
F	10.03		10.34	0.395		0.407	
G		4.90			0.193		
Н	12.45		12.95	0.490		0.510	
I		2.54			0.100		
J	17.53		18.03	0.690		0.710	
К	22.61		23.11	0.890		0.910	
L	0.08		0.15	0.003		0.006	
М	1.32		1.83	0.052		0.072	
N	2.84		3.35	0.112		0.132	
Р			5.84			0.230	



Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

The ST logo is registered trademark of STMicroelectronics ® 2001 STMicroelectronics - All Rights Reserved

All other names are the property of their respective owners.

STMicroelectronics GROUP OF COMPANIES

Australia - Brazil - China - Finland - France - Germany - Hong Kong - India - Italy - Japan - Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - U.S.A.

http://www.st.com

4